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Formulated to prolong tip life in the harsh soldering environments of rosin, no-clean and water soluble fluxes. Flux usage allows oxide build-up on tip, causing poor thermal transfer and dewetting of the tip surface. Use on standard tips.

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DRAWING TITLE:				1/2 OZ. LEAD FREE TIP TINNER			
SIZE	DWG. NO.	ELECTRONIC FILE	REV	SCALE:	NTS	U.O.M.: INCHES [mm]	SHEET:
A	1471	10N694.DWG	A				1 OF 1